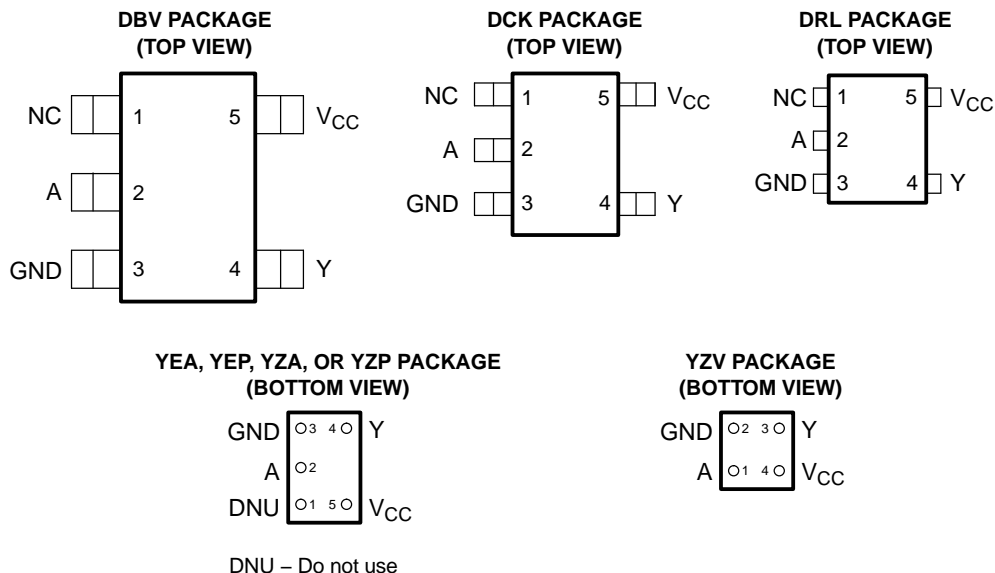


## FEATURES

- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Supports 5-V  $V_{CC}$  Operation
- Input and Open-Drain Output Accept Voltages up to 5.5 V
- Max  $t_{pd}$  of 4.2 ns at 3.3 V
- Low Power Consumption, 10- $\mu$ A Max  $I_{CC}$
- $\pm 24$ -mA Output Drive at 3.3 V
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

## DESCRIPTION/ORDERING INFORMATION

This single buffer/driver is designed for 1.65-V to 5.5-V  $V_{CC}$  operation.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

The output of the SN74LVC1G07 device is open drain and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions. The maximum sink current is 32 mA.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

NanoStar, NanoFree are trademarks of Texas Instruments.

# SN74LVC1G07

## SINGLE BUFFER/DRIVER

### WITH OPEN-DRAIN OUTPUT

SCES296T–FEBRUARY 2000–REVISED OCTOBER 2005

#### ORDERING INFORMATION

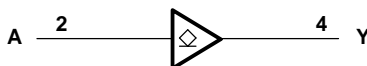
T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING <sup>(2)</sup>
–40°C to 85°C	NanoStar™ – WCSP (DSBGA) 0.17-mm Small Bump – YEA	Reel of 3000	SN74LVC1G07YEAR	---CV_
	NanoFree™ – WCSP (DSBGA) 0.17-mm Small Bump – YZA (Pb-free)		SN74LVC1G07YZAR	
	NanoStar™ – WCSP (DSBGA) 0.23-mm Large Bump – YEP		SN74LVC1G07YEPR	
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZP (Pb-free)		SN74LVC1G07YZPR	
	NanoFree™ – WCSP (DSBGA) 0.23-mm Large Bump – YZV (Pb-free)	Reel of 3000	SN74LVC1G07YZVR	--CV
	SOT (SOT-23) – DBV	Reel of 3000	SN74LVC1G07DBVR	C07_
		Reel of 250	SN74LVC1G07DBVT	
	SOT (SC-70) – DCK	Reel of 3000	SN74LVC1G07DCKR	CV_
		Reel of 250	SN74LVC1G07DCKT	
	SOT (SOT-553) – DRL	Reel of 4000	SN74LVC1G07DRLR	CV_

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).
- (2) DBV/DCK/DRL: The actual top-side marking has one additional character that designates the assembly/test site.  
 YEA/YEP, YZA/YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).  
 YZV: The actual top-side marking is on two lines. Line 1 has four characters to denote year, month, day, and assembly/test site. Line 2 has two characters which show the family and function code. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).

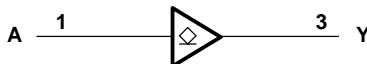
#### FUNCTION TABLE

INPUT A	OUTPUT Y
H	H
L	L

#### LOGIC DIAGRAM (POSITIVE LOGIC) (DBV, DCK, DRL, YEA, YEP, YZA, and YZP Package)



#### LOGIC DIAGRAM (POSITIVE LOGIC) (YZV Package)



## Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	–0.5	6.5	V
$V_I$	Input voltage range <sup>(2)</sup>	–0.5	6.5	V
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	–0.5	6.5	V
$V_O$	Voltage range applied to any output in the high or low state <sup>(2)(3)</sup>	–0.5	6.5	V
$I_{IK}$	Input clamp current	$V_I < 0$		–50 mA
$I_{OK}$	Output clamp current	$V_O < 0$		–50 mA
$I_O$	Continuous output current			±50 mA
	Continuous current through $V_{CC}$ or GND			±100 mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DBV package		206
		DCK package		252
		DRL package		142
		YEA/YZA package		154
		YEP/YZP package		132
		YZV package		116
$T_{stg}$	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of  $V_{CC}$  is provided in the recommended operating conditions table.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

# SN74LVC1G07

## SINGLE BUFFER/DRIVER

### WITH OPEN-DRAIN OUTPUT

SCES296T–FEBRUARY 2000–REVISED OCTOBER 2005

#### Recommended Operating Conditions<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$ Supply voltage	Operating	1.65	5.5	V
	Data retention only	1.5		
$V_{IH}$ High-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$		V
	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7		
	$V_{CC} = 3\text{ V to }3.6\text{ V}$	2		
	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	$0.7 \times V_{CC}$		
$V_{IL}$ Low-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$		$0.35 \times V_{CC}$	V
	$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		0.7	
	$V_{CC} = 3\text{ V to }3.6\text{ V}$		0.8	
	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		$0.3 \times V_{CC}$	
$V_I$ Input voltage		0	5.5	V
$V_O$ Output voltage		0	5.5	V
$I_{OL}$ Low-level output current	$V_{CC} = 1.65\text{ V}$		4	mA
	$V_{CC} = 2.3\text{ V}$		8	
	$V_{CC} = 3\text{ V}$		16	
			24	
	$V_{CC} = 4.5\text{ V}$		32	
$\Delta t/\Delta v$ Input transition rise or fall rate	$V_{CC} = 1.8\text{ V} \pm 0.15\text{ V}, 2.5\text{ V} \pm 0.2\text{ V}$		20	ns/V
	$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		10	
	$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		5	
$T_A$ Operating free-air temperature		–40	85	°C

(1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

#### Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{CC}$	MIN	TYP <sup>(1)</sup>	MAX	UNIT
$V_{OL}$	$I_{OL} = 100\text{ }\mu\text{A}$	1.65 V to 5.5 V			0.1	V
	$I_{OL} = 4\text{ mA}$	1.65 V			0.45	
	$I_{OL} = 8\text{ mA}$	2.3 V			0.3	
	$I_{OL} = 16\text{ mA}$	3 V			0.4	
	$I_{OL} = 24\text{ mA}$				0.55	
	$I_{OL} = 32\text{ mA}$	4.5 V			0.55	
$I_I$ A input	$V_I = 5.5\text{ V or GND}$	0 to 5.5 V			$\pm 5$	$\mu\text{A}$
$I_{off}$	$V_I \text{ or } V_O = 5.5\text{ V}$	0			$\pm 10$	$\mu\text{A}$
$I_{CC}$	$V_I = 5.5\text{ V or GND}, I_O = 0$	1.65 V to 5.5 V			10	$\mu\text{A}$
$\Delta I_{CC}$	One input at $V_{CC} - 0.6\text{ V}$ , Other inputs at $V_{CC}$ or GND	3 V to 5.5 V			500	$\mu\text{A}$
$C_i$	$V_I = V_{CC}$ or GND	3.3 V			4	pF
$C_o$	$V_O = V_{CC}$ or GND	3.3 V			5	pF

(1) All typical values are at  $V_{CC} = 3.3\text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

#### Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

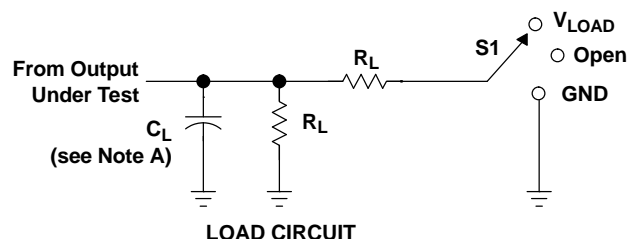
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V} \pm 0.15\text{ V}$		$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$		$V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$		$V_{CC} = 5\text{ V} \pm 0.5\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A	Y	2.4	8.3	1	5.5	1.5	4.2	1	3.5	ns

## Operating Characteristics

$T_A = 25^\circ\text{C}$

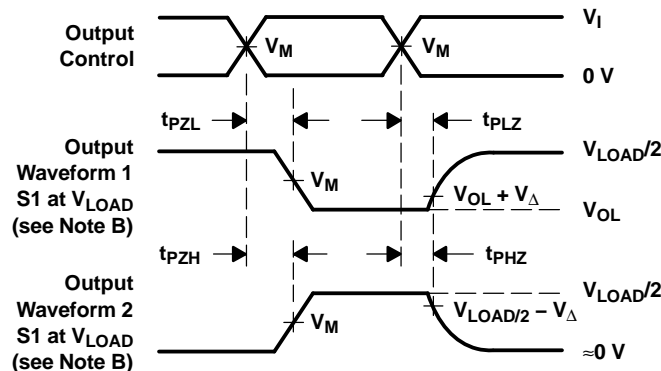
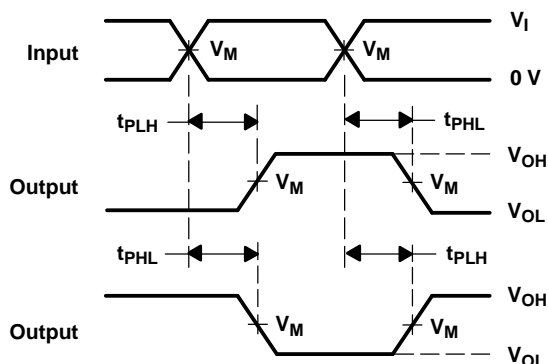
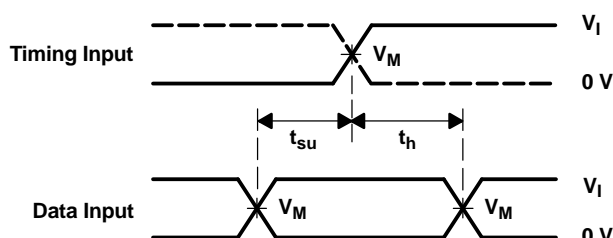
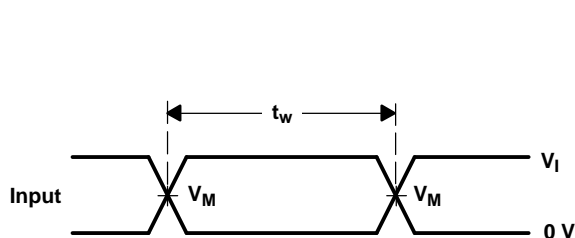
PARAMETER	TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	$V_{CC} = 5\text{ V}$	UNIT
		TYP	TYP	TYP	TYP	
$C_{pd}$ Power dissipation capacitance	$f = 10\text{ MHz}$	3	3	4	6	pF

## PARAMETER MEASUREMENT INFORMATION (OPEN DRAIN)



TEST	S1
$t_{PZL}$ (see Notes E and F)	$V_{LOAD}$
$t_{PLZ}$ (see Notes E and G)	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	$V_{LOAD}$

$V_{CC}$	INPUT		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	$V_{CC}$	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 $\Omega$	0.3 V



- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics: PRR  $\leq 10\text{ MHz}$ ,  $Z_O = 50\text{ }\Omega$ .
  - The outputs are measured one at a time, with one transition per measurement.
  - Since this device has open-drain outputs,  $t_{PLZ}$  and  $t_{PZL}$  are the same as  $t_{pd}$ .
  - $t_{PZL}$  is measured at  $V_M$ .
  - $t_{PLZ}$  is measured at  $V_{OL} + V_{\Delta}$ .
  - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LVC1G07DBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G07DBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G07DBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G07DBVTE4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G07DCKR	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G07DCKRE4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G07DCKRG4	ACTIVE	SC70	DCK	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G07DCKT	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G07DCKTE4	ACTIVE	SC70	DCK	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G07DRLR	ACTIVE	SOP	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G07DRLRG4	ACTIVE	SOP	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC1G07YEAR	ACTIVE	WCSP	YEA	5	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74LVC1G07YEPR	ACTIVE	WCSP	YEP	5	3000	TBD	SNPB	Level-1-260C-UNLIM
SN74LVC1G07YZAR	ACTIVE	WCSP	YZA	5	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM
SN74LVC1G07YZPR	ACTIVE	WCSP	YZP	5	3000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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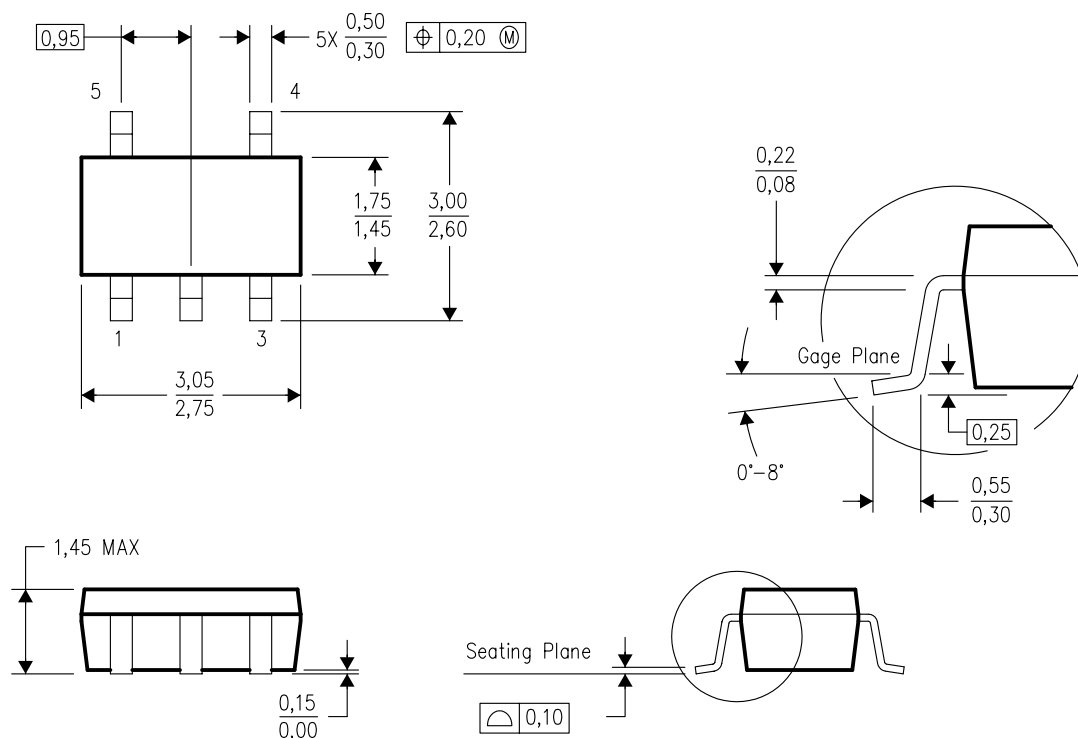
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## DBV (R-PDSO-G5)

## PLASTIC SMALL-OUTLINE PACKAGE

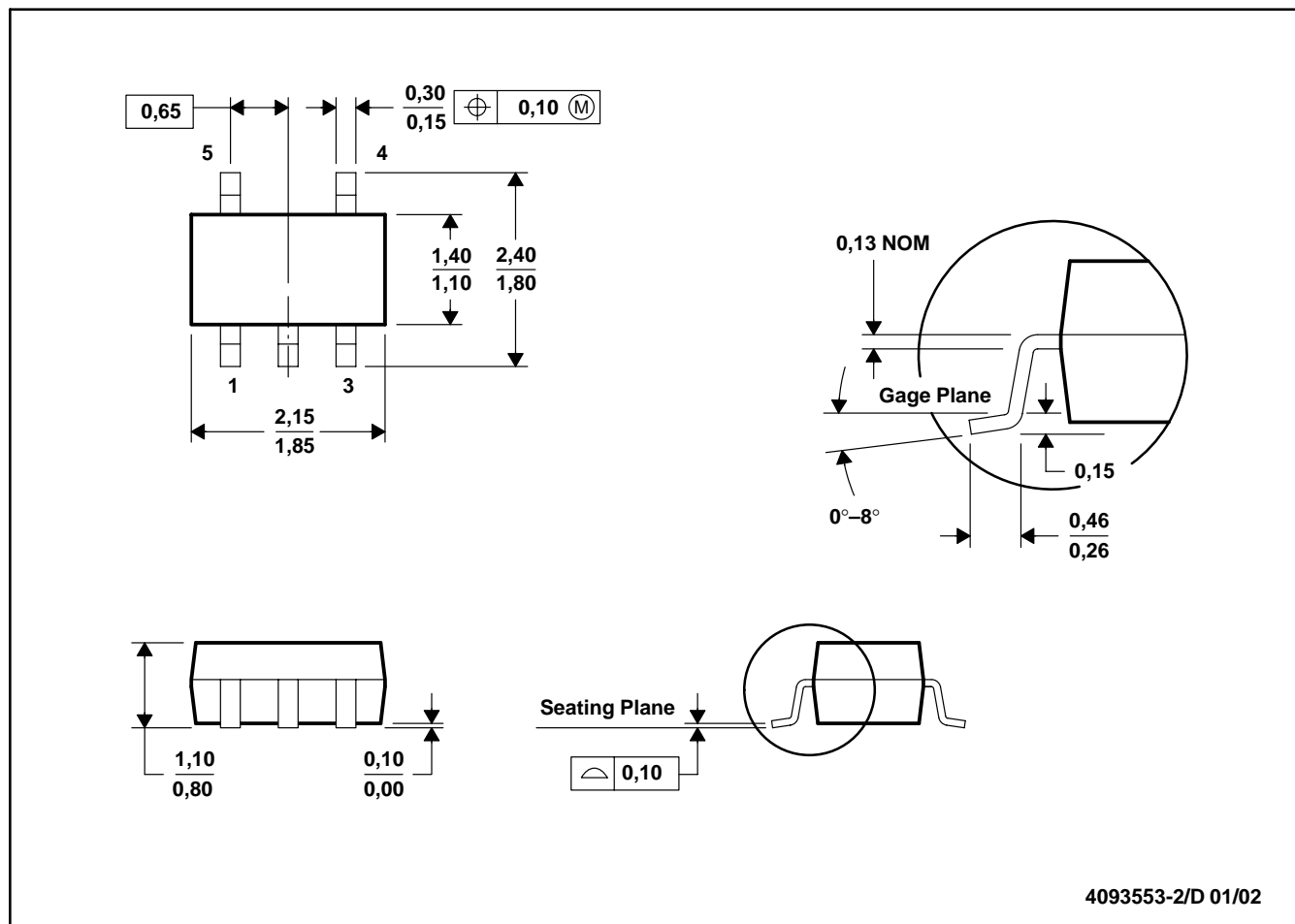


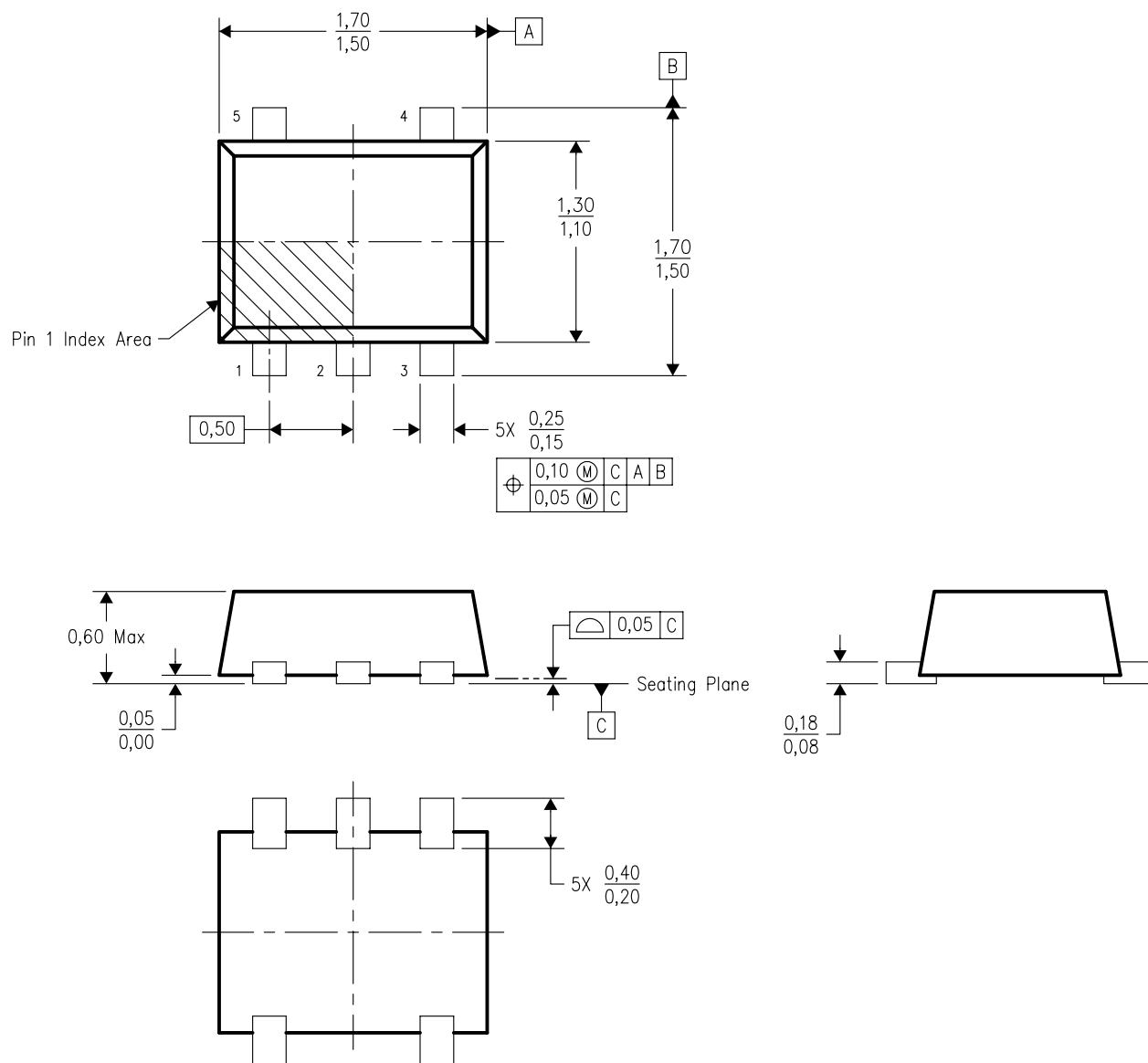
4073253-4/J 10/2005

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-178 Variation AA.

## DCK (R-PDSO-G5)

## PLASTIC SMALL-OUTLINE PACKAGE



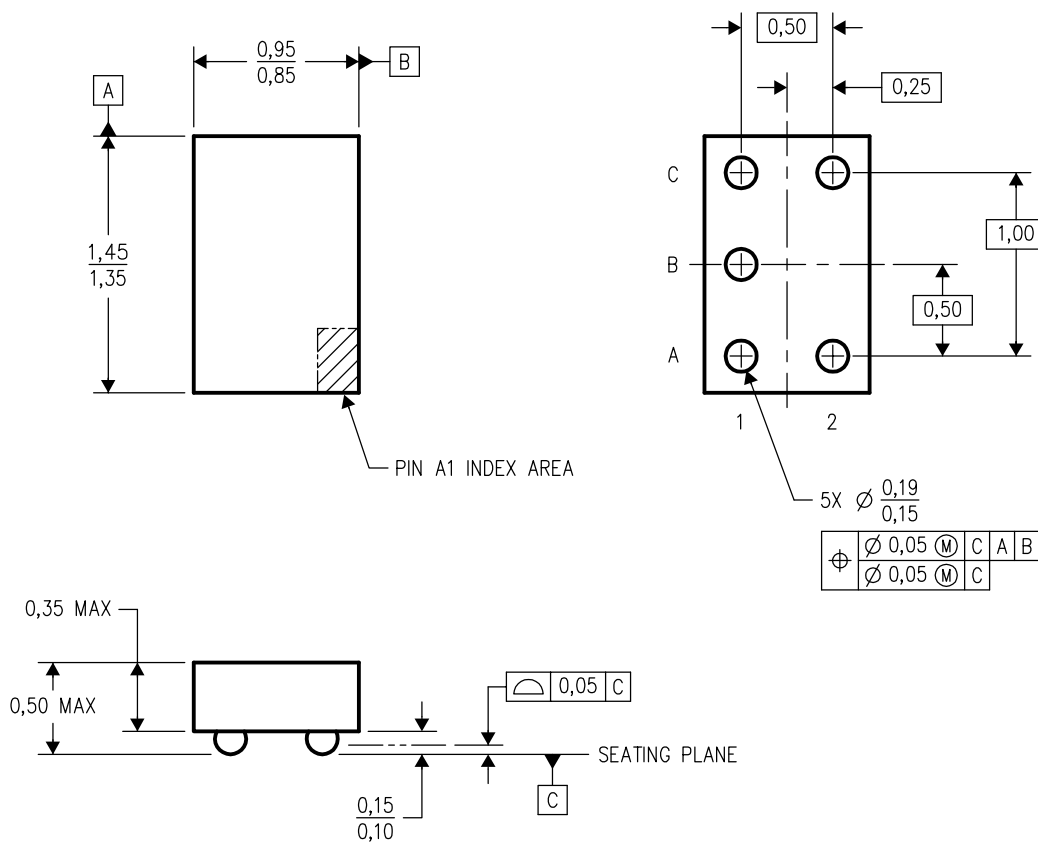


4205622-2/B 07/2004

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. JEDEC package registration is pending.

## YEA (R-XBGA-N5)

## DIE-SIZE BALL GRID ARRAY



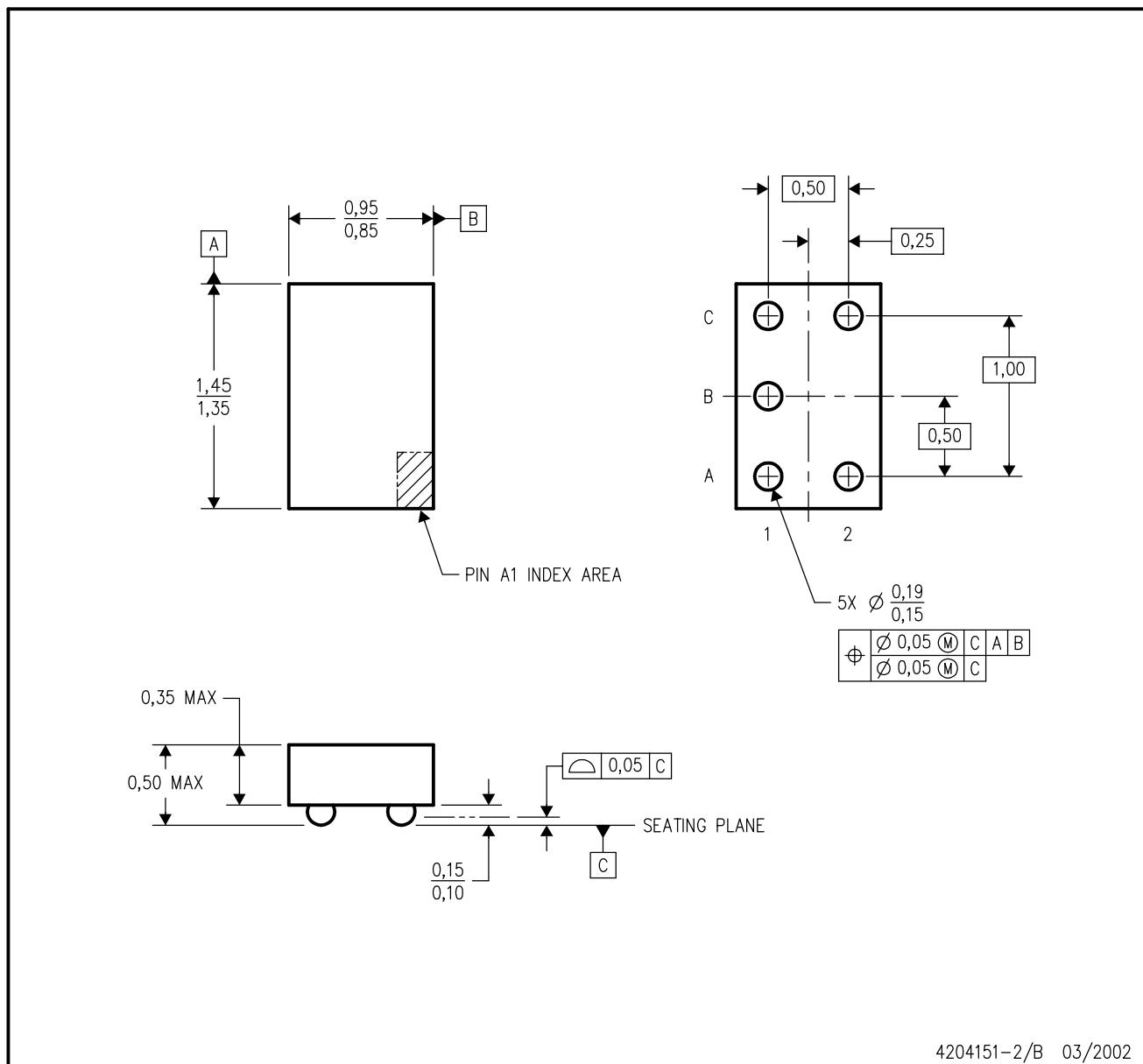
4203167-2/C 04/2002

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoStar™ package configuration.
  - D. Package complies to JEDEC MO-211 variation EA.
  - E. This package is tin-lead (SnPb). Refer to the 5 YZA package (drawing 4204151) for lead-free.

NanoStar is a trademark of Texas Instruments.

## YZA (R-XBGA-N5)

## DIE-SIZE BALL GRID ARRAY

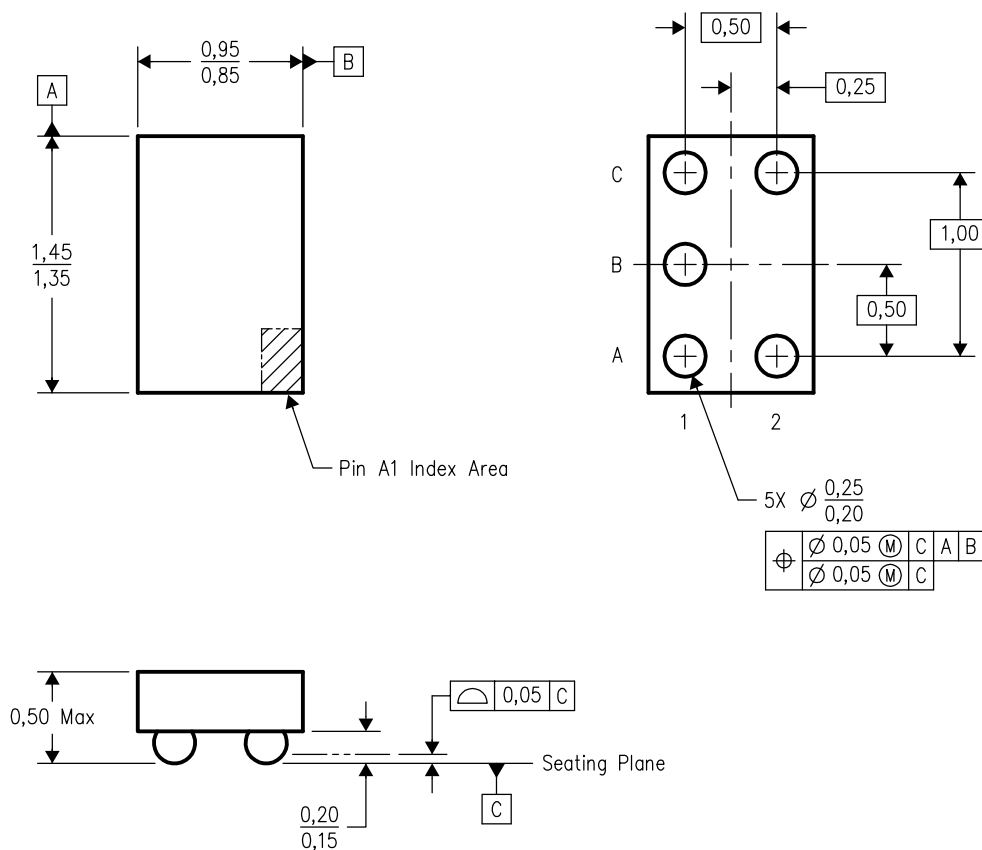


- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - D. Package complies to JEDEC MO-211 variation EA.
  - E. This package is lead-free. Refer to the 5 YEA package (drawing 4203167) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.

## YZP (R-XBGA-N5)

## DIE-SIZE BALL GRID ARRAY



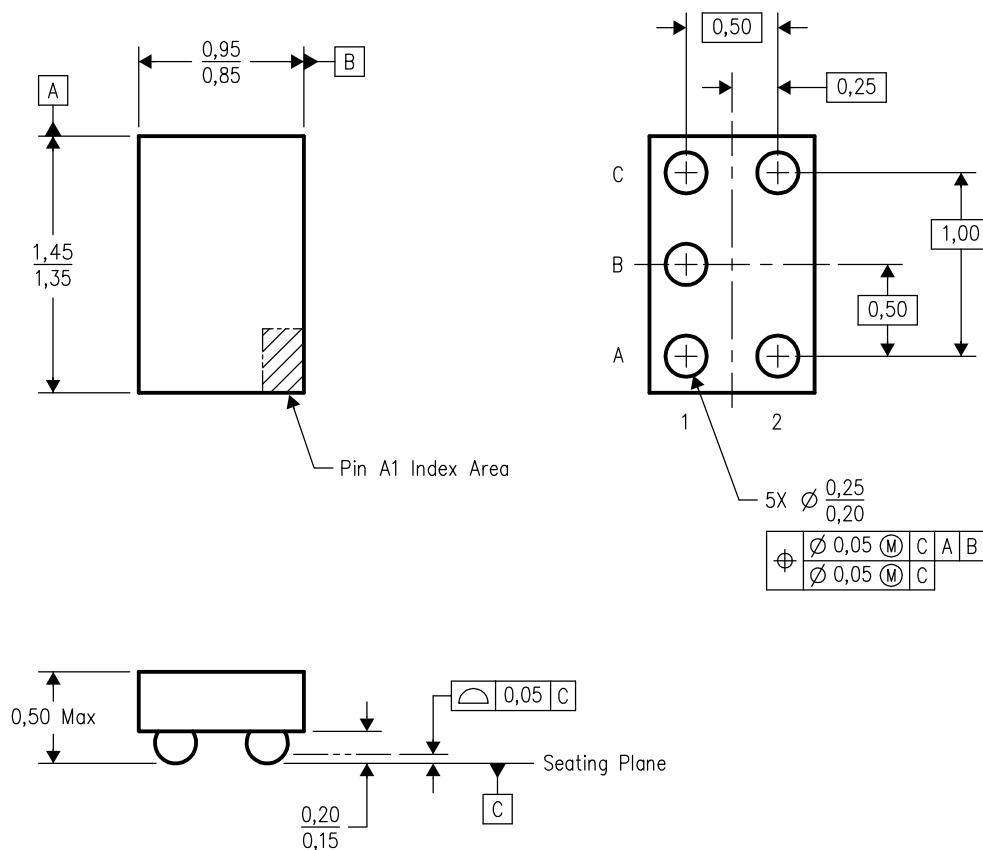
4204741-2/A 10/2002

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoFree™ package configuration.
  - D. This package is lead-free. Refer to the 5 YEP package (drawing 4204725) for tin-lead (SnPb).

NanoFree is a trademark of Texas Instruments.

YEP (R-XBGA-N5)

DIE-SIZE BALL GRID ARRAY



4204725-2/A 10/2002

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. NanoStar™ package configuration.
  - D. This package is tin-lead (SnPb). Refer to the 5 YZP package (drawing 4204741) for lead-free.

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DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Broadband	<a href="http://www.ti.com/broadband">www.ti.com/broadband</a>
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